IN THE CLAIMS:

Please add new claims 29-33 as follows.

1-17. (Cancelled)

18. (Previously Presented) An exposure method of exposing a substrate to a pattern, in which a mark in each of a plurality of layers on the substrate is detected for alignment of the substrate, said method comprising steps of:

illuminating a mark in each of a plurality of layers on a substrate;

detecting an image of the illuminated mark in each of the plurality of layers; and

setting an illumination condition in said illuminating step for the mark in each of the plurality of layers.

19. (Previously Presented) A method according to claim 18, wherein the illumination condition includes at least one of a kind of a detection system which illuminates a mark and detects an image of the illuminated mark, a kind of a light source, a wavelength of light and an intensity distribution of light.

20. (Previously Presented) A method according to claim 18, wherein, in said setting step, the illumination condition is set based on a manual indication.

21. (Previously Presented) A method according to claim 20, wherein the manual indication is performed through a manual switching part.

22. (Previously Presented) A method according to claim 18, wherein, in said setting step, the illumination condition is set with respect to each of the plurality of layers.

23. (Previously Presented) A method according to claim 18, wherein the illumination condition is set based on the detected image.

24. (Previously Presented) A method according to claim 23, wherein the image of the illuminated mark in each of the plurality of layers is detected in each of a plurality of illumination conditions, and the illumination condition is set for the mark in each of the plurality of layers based on the detected images.

25. (Previously Presented) A method according to claim 24, wherein the illumination condition is set for the mark in each of the plurality of layers based on a contrast of each of the detected images.

26. (Previously Presented) A method according to claim 24, wherein the setting is performed for each lot of the substrate.

27. (Previously Presented) A method according to claim 18, wherein said illuminating step includes steps of:

illuminating each first mark in a first layer in a first illumination condition; and

illuminating each second mark in a second layer in a second illumination condition.

28. (Previously Presented) A method according to claim 27, further comprising:

a step of calculating a position of each region on the substrate based on each detected image for the illuminated first mark and each detected image for the illuminated second mark.

29. (New) An exposure apparatus for exposing a substrate to a pattern, said apparatus detecting a mark in each of a plurality of layers on the substrate for alignment between the substrate and the pattern, said apparatus comprising:

a detection system which illuminates a mark on the substrate and detects an image of the illuminated mark; and

a setting system which sets an illumination condition of said detection system for a plurality of marks, used for alignment, on the substrate, with respect to each of the plurality of layers.

30. (New) An apparatus according to claim 29, wherein the illumination condition includes at least one of a kind of said detection system, a kind of a light source, a wavelength of light and an intensity distribution of light.

31. (New) An apparatus according to claim 29, wherein said setting system sets the illumination condition based on a manual indication.

32. (New) An apparatus according to claim 31, wherein said setting system includes a manual switching part.

33. (New) A device manufacturing method comprising:

a step of exposing a substrate to a pattern using an exposure apparatus recited in claim 29.